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ABSTRACT OF THE DISCLOSURE

The present invention provides a method for manufacturing a semiconductor device comprising steps of: bonding one 5 semiconductor chip to each of multiple mounting portions of a substrate; covering the semiconductor chips bonded to the mounting portions with a common resin layer; bringing the substrate into contact with the resin layer and gluing the substrate to an adhesive sheet; and performing dicing and 10 measurement for the semiconductor chips that are glued to the adhesive sheet.

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